

Packaging Module

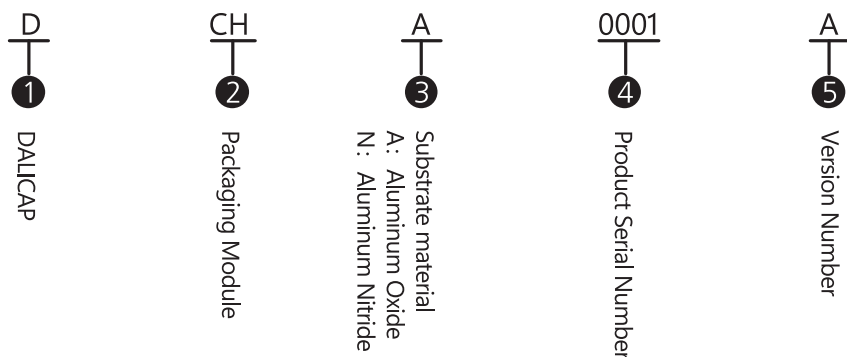
◆ Product Characteristics

1. Through the potting and packaging protection process, the circuit has moisture-proof, insulation, anti-corrosion and other properties, which effectively extends the service life of the product;
2. Customers can directly connect the module to the device circuit to simplify the assembly process.

◆ Product Applications

High-power semiconductor equipment, new energy and other fields.

◆ Part Number



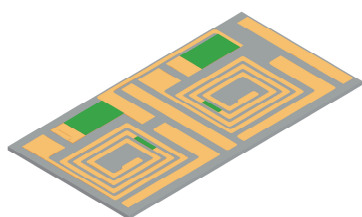
◆ Process Introduction

Modules are electronic components with independent functions that solder electronic components (such as capacitors, resistors, diodes, etc.) with specific functions onto ceramic circuits through reflow soldering process. They can be directly connected to the device circuit to perform specific functions, and offer protection, interconnection and other characteristics. Modules can be customized according to customer needs.

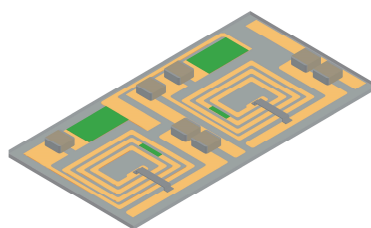
◆ Delivery Form

Based on customer's customization requirements, the following products are available:

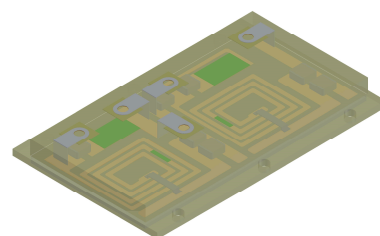
1. Ceramic circuit substrate (can include thick film resistors)
2. Module (capacitors, resistors, diodes, connecting sheets etc., are mounted on the ceramic circuit substrate)
3. Packaging module(after the module is potted, protective shell and leads are installed)



Ceramic circuit substrate



Module



Packaging module